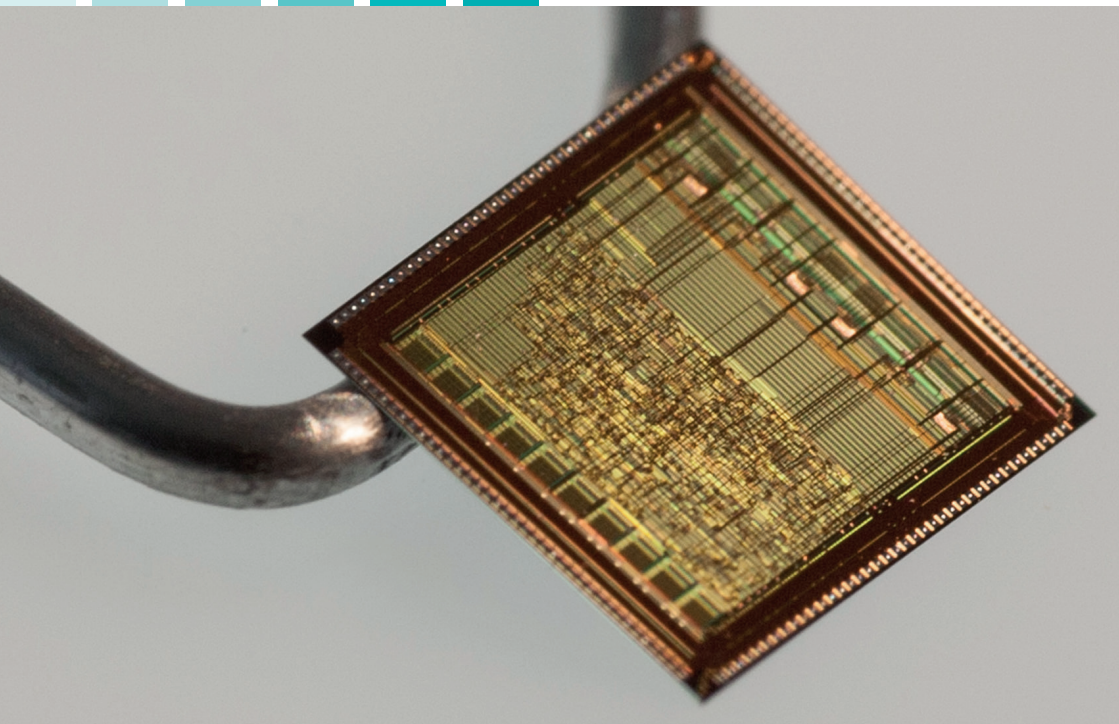
An Ultra-thin CMOS Sensor for In-plane Stress Sensing

Yiğit Uygar Mahsereci



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To all my heroes

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